

XIVI

SEMICONDUCTOR
Automation Solutions

XIVI's Advantages

1 Deep Technical Expertise

Ten years of expertise, backed by multiple invention patents.

2 Standardized Module Library

Extensive standard module library for rapid configuration and customization.

3 Continuous innovation

In-house R&D ensuring continuous product iteration.

4 Mature Manufacturing & Quality Control

Comprehensive production system with strict quality controls.

5 Cost, Supply Chain & Pricing Advantage

In-house machining & supply chain for low-cost operations.

6 Comprehensive Global Service Network

Service networks across Asia-Pacific, and the Americas.

XIVI's Data items

10 years

Our company has been established for more than 10 years.

23200 m²

Wuxi R&D and manufacturing cover an area of 22000 m².

The Shanghai R&D department covers an area of 1200 m².

400 +

We have more than 400 employees. R&D and technical personnel account for nearly 35%.

15%

The expense for research and development accounts for more than 15% of the operating revenue.

3000 +

More than 3000 self-developed stages have been delivered.

500 +

More than 500 self-developed EFEM have been delivered.

ABOUT XIVI

With nearly 10 years of experience in precision motion control research and development, xivi has gathered expertise in the precision manufacturing industry to form the development strategy of "Ultra-precision Positioning, Transmission and Storage Solution Manufacturer".

Pursuing micron and nanometer precision motion control technology, practicing precision manufacturing capabilities and excellent production management, we are committed to providing innovative industrial products for the industrial automation market.

Thinker In Motion

星微科技

Semiconductor Automation Solutions

EFEM

SORTER

VTM
AMR

Robot ZTR-W

Robot VTR
Robot STR

Ports

Aligner



Equipped with direct-drive servo motors, clean Robot, Aligner, and linear Track to achieve high throughput for 6", 8", and 12" wafers. SEMI standard FOUP, FOSB, Open Cassette, SMIF Port and other loading units can be matched according to different needs, and mix and match of loading units is also possible.

Feature

- ▶ High throughput can be achieved with the optional 2 Aligners.
- ▶ Compatible with 150/200/300mm Wafer.
- ▶ Vacuum pick-and-place and edge-grip pick-and-place (optional).
- ▶ OHT, AGV can correspond.

Optional

- ▶ E84
- ▶ OCR
- ▶ Lonizer
- ▶ Teaching pendant
- ▶ Chemical Filter
- ▶ Autoteaching
- ▶ Compatible with Barcode Reader and RF-ID Reader.

Specifications

Model Number	VEM2200	VEM2300	VEM2400
Number of Ports	2	3	4
Target of transmission	300mm Wafer $\varnothing 300 \pm 0.2\text{mm}$		
Carriers	300mm FOUP 25 segments (SEMI E47.1)		
	300mm FOSB 25 segments (SEMI E31)		
Power Supply	Single-phase AC200V~AC220V $\pm 10\%$ 50/60Hz $\pm 5\%$		
Electric current	4kVA(20A/200VAC) include FFU		
Vacuum (pressure)	-80kPa ~ -90kPa		
Vacuum (flow)	40L/min	50L/min	60L/min
Positive pressure (pressure)	0.6MPa ~ 0.7MPa		
Positive pressure (flow)	20L/min	30L/min	40L/min

Feature

- ▶ Compatible with 200mm/300mm Wafer
- ▶ Multiple pick & place options
- ▶ Reads IDs from top and bottom of wafer.
- ▶ OHT, AGV can be corresponded
- ▶ Optional edge detection function

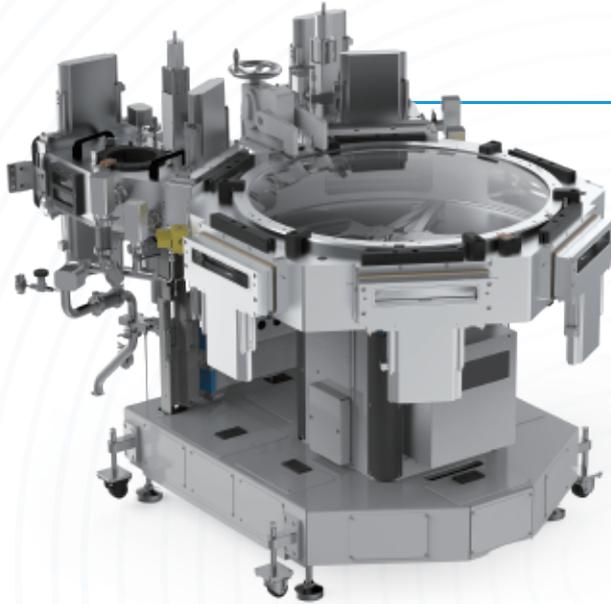
Specifications

Model number	SW2200	SW2300	SW2400
Number of Ports	2	3	4
Target of Transmission	300mm Wafer $\phi 300 \pm 0.2\text{mm}$		
Carriers	300mm FOUP 25(SEMI E47.1)		
	300mm FOSB 25(SEMI M31)		
Power Supply	Single-phase AC200V~AC220V $\pm 10\%$ /50/60Hz $\pm 5\%$		
Electric Current	4kVA(20A/200VAC) include FFU		
Vacuum (pressure)	-80kPa ~ -90kPa		
Vacuum (flow)	40L/min	50L/min	60L/min
Positive Pressure (pressure)	0.6MPa ~ 0.7MPa		
Positive Pressure (flow)	20L/min	30L/min	40L/min



High throughput is achieved by adopting a clean robot and Aligner with direct-drive servo motors. Loadport can add various units to the front, back, and sides of the frame, and can be directly interfaced with OHT and AGV.

VTM



Vacuum Transfer Module (VTM) is an efficient transfer equipment based on the principle of negative vacuum pressure, which consists of vacuum generator, transfer pipeline, carrying device and control system, and drives the material along the pipeline through the pressure difference. It has the advantages of high efficiency and fast transmission, avoiding material contamination from the outside world, smooth operation, low noise, small footprint, etc. It can be flexibly adapted to automated production lines.

AMR

AMR (Autonomous Mobile Robot) is based on artificial intelligence and autonomous navigation technology, real-time perception of the environment through LIDAR, vision sensors, SLAM (real-time localization and map construction) technology, autonomous planning of the optimal path for high-precision, high-cleanliness scenarios of the wafer box automated handling, to meet the stringent requirements of the clean room, to help semiconductor production lines to achieve the core objective of zero pollution, zero error. Help semiconductor production lines to realize the core objectives of zero pollution and zero error in material transfer.



XIVI's vacuum manipulators have a full link arm mechanism for higher positioning accuracy. Adopting full closed-loop control and equipped with vacuum direct-drive motors, it has higher rotary accuracy and faster response time. The bidirectional dual-arm configuration allows for longer transfer distances than conventional models without enlarging the chamber, and has higher work efficiency in the face of multiple work stations.

Specifications

Specifications		
Wafer Size	6" / 8" / 12"	
Motion Range	Lifting Stroke (Z-axis)	70 mm / 125 mm
	Rotary Stroke (T-axis)	360° (Unlimited rotation)
	Telescopic Stroke (R-axis)	1050 mm (Depending on the fork change)
Repeat Positioning Accuracy	Z-axis	±0.05 mm
	T-axis	±0.006°
	R-axis	±0.05 mm
Body Weight	38 kg	
Vacuum Resistance	1×10^{-6} Pa	
Leakage Rate	$< 1 \times 10^{-9}$ std · cc/sec He	
Cleanliness Level	ISO Class 1	
Communication Protocols	TCP / IP	
Optional	AWC (Wafer position correction)	





The Atmospheric Wafer Transfer Robot (hereinafter referred to as the 'Robot') is suitable for use in atmospheric clean room environments, and consists of a body, an arm, and End effector(optional), and realises wafer transfer functions by means of suction, gripping, etc., and cyclic movements of each joint. The motion of the robot is divided into lifting motion (Z-axis), rotary motion (T-axis), and arm extension/retraction motion (R/W-axis).

Naming Convention

VTR	-	00	-	00	-	00	-	250	-	143	-	00	-	00	-	001
Series	Quantities	Flip Mechanism Type	Mapping Sensor	Z-axis Motion Range	Arm Length	End Effector	Fixing Method	Serial Number								
VTR	00-Single-arm 01-Dual arms	00-Upper arm flip 01-Lower arm flip 02-Double-armed flip 03-No flip	00-With mapping sensor 01-Without mapping sensor	250mm 300mm 350mm 400mm 450mm	143.5mm 176mm	00-Vacuum-suction type 01-Gripper type 02-Bernoulli 99-Other	00-Base plate mounting 01-Upper plate mounting 99-Other	001 002 003								

Specifications

VTR		Single-arm	Dual-arm
		143.5mm / 176mm	
Payload		0.5 kg	
R/W axis	Speed	360mm/s	
T axis	Range of Motion	0°~340°	
	Speed	250°/s	
Z axis	Range of Motion	250/300/350/400/450mm	
	Speed	250mm/s	
Approx.Mass		Approx. 37kg	
Cleanliness		Class1	
Repeatability		± 0.1 mm	
Rated Voltage and Current		Single-phase AC 200V 20A	

The payload is the weight of the product being transferred.

Naming Convention

STR	-	00	-	03	-	00	-	480	-	440	-	00	-	00	-	001
Series	Quantities	Flip Mechanism Type	Mapping Sensor	Z-axis Motion Range	Arm Length	End Effector	Fixing Method	Serial Number								
STR	00-Single-arm 01-Dual-arms	00-Upper arm flip 03-No flip	00-Swept film 01-Swipe-free	480mm	440mm	00-Vacuum-suction type 01-Gripper type 02-Bernoulli 99-Other	00-Base plate mounting 01-Upper plate mounting 99-Other	001 002 003								

Specifications

STR		Single-arm
▶ Payload		440mm
R/W axis	Speed	0.5 kg
	Range of Motion	350°/s
T axis	Speed	± 310° ~ ±130°
	Range of Motion	260°/s
H axis	Speed	± 165°
	Range of Motion	330°/s
Z axis	Speed	± 165°
	Range of Motion	550mm/s
Approx. Mass		480mm
Cleanliness		45-50kg
Repeatability		Class 1
Rated Voltage and Current		± 0.1mm
		Single-phase AC 200V 20A

▶ The rated load is the weight of the product being transferred.



5-axis semiconductor wafer handling robot with 2 independently controllable rotary arms. It can support wafer pickup of EFEM from 2 FOUP to 3 FOUP. The robot has high precision and high rigidity.



Open Cassette



Load Port



SMIF

Optional

▶ Load Port

- ▶ E84.
- ▶ 8" / 12" Wafers.
- ▶ Customizable Indicator Lights.
- ▶ Compatible with Barcode Reader / RFID Reader.
- ▶ Info Pad Pin and Lockout Pin.
- ▶ External I/O Interface.
- ▶ TCP/IP Communication.

▶ SMIF

- ▶ E84.
- ▶ External I/O Interface.
- ▶ Customizable Indicator Lights.
- ▶ Compatible with Smart Tag Reader / RFID Reader.
- ▶ 6" / 8" Wafers.
- ▶ TCP/IP Communication.

Specifications

▶ Load Port

Supported FOUPs	300mm FOUPs compliant with SEMI E47.1 and E62	
Principal Dimensions	1384(H) x 472(W) x 471(D)mm	
Weight	60 kg	
Power Supply	AC 220V±10%, 50 Hz±5%, 5A	
Communication Interface	EtherCAT	
Precision	Stroke	70mm
	Repeatability	±0.05mm
Operating Environment	Temperature	5 - 40°C
	Humidity	30 - 80%

▶ SMIF

Supported SMIF Pods	Interface compliant with SEMI E19.4	
Principal Dimensions	1384(H) x 472(W) x 479(D)mm	
Weight	50 kg	
Power Supply	DC 24V / AC 220V±10%, 50 Hz±5%, 5A	
Communication Interface	EtherCAT	
Precision	Stroke	263mm
	Repeatability	±0.05mm
	Docking Accuracy	Center Offset <15mm
Operating Environment	Temperature	5 - 40°C
	Humidity	30 - 80%



Feature

- ▶ Increasing productivity.
- ▶ Handling of transparent glass wafers and bonded wafers.
- ▶ Notch angular accuracy, center accuracy vary depending on sensor and wafer size.
- ▶ Alignment time is the processing time at standard accuracy, and the Alignment time varies depending on the wafer size.

Specifications

WAFER SIZE	Positioning accuracy		Positioning interval
	Notch angular accuracy	Centre accuracy	
ø100 ~ ø300	±0.05° ~ ±0.1°	±0.1mm	2~6 seconds

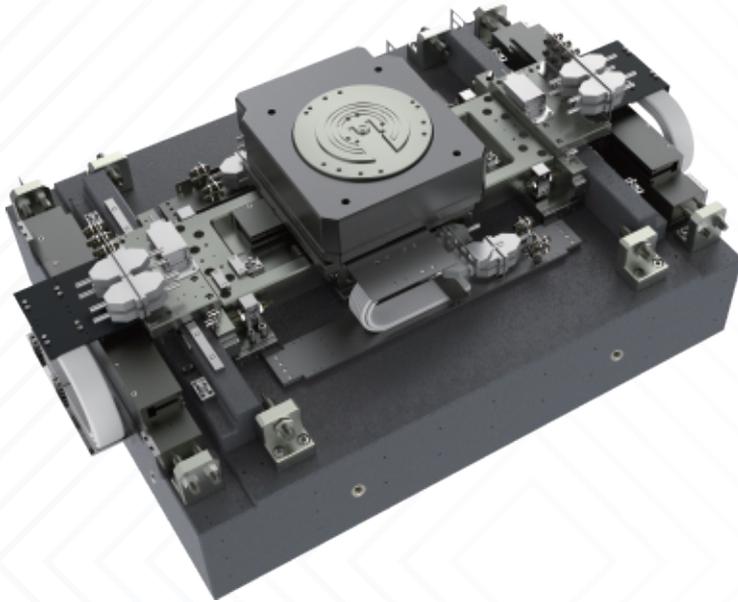
Mechatronics Systems & Components

ABXY

VMS-V

VMZT

Self-developed
motion control
components



The ABXY-ZT4 series stage is an air-bearing, mechanical motion stage with six degrees of freedom. It is specially designed for back-channel exposure machine and wafer inspection, slicing, annealing and other demanding semiconductor industry design.

Feature

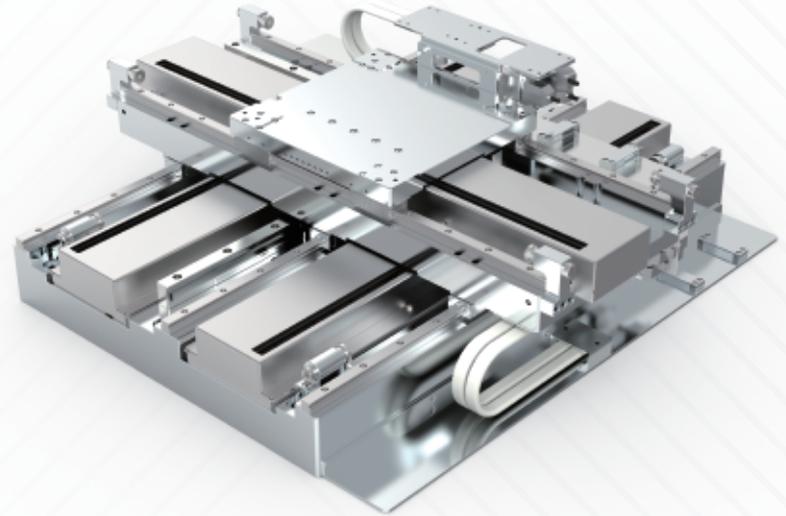
- ▶ X, Y adopts air-floating bearings, smooth operation
- ▶ T-axis: arbitrary micro-rotation for levelling
- ▶ Dual-drive stepper shaft with passive vibration damping module
- ▶ Z-axis: fast, precise focusing movement

Specifications

SPECIFICATIONS		
Travel	Scan Axis	350mm,500mm,
	Step Axis	350mm,500mm
	Z Axis	5mm
	Tip/Tilt Axis	±2mrad
	Rz	±3°
Drive System	Linear Brushless Motor	
Resolution	<1 nm	
Accuracy	±200nm	
Repeatability (choose linear driver)	±100nm (±50 nm Optional)	
XYZ Position Stability (Air On)	20 nm	
Granite Bass Thickness	250mm	
Rated Payload(Maintaining Dynamic Specifications)	5kg	
Maximum Payload	10 kg	
Maximum Velocity with Rated Payload	Scan Step Axis	400 mm/s
Peak Acceleration with Rated Payload	Scan Step Axis	1G(10m/s)
RMS Acceleration with Rated Load	Scan Step Axis	0.5G(5m/s)
Stiffness,First Natural Frequency with Rated Payload	>100Hz	
Pitch	2 arc sec	
Roll	2 arc sec	
Yaw	2 arc sec	
XY straightness	1um	
XY Flatness	1.2um	
XY Orthogonality	<2 arc sec	
Velocity ripple(sampled at 400mm/s)	0.1%	
MTBF	20,000 hours	

Specifications

VMS-V	lower axis	upper axis
Axis	X	Y
Travel	400mm	400mm
Repeat Positioning Accuracy	±0.3µm	±0.3µm
Maximum speed	0.35m/s	0.35m/s
maximum acceleration	0.4g	0.4g
horizontal straightness	±1µm	±2µm
vertical straightness	±2µm	±2µm
pitch angle	8arcsec	8arcsec
angle of drift	8arcsec	8arcsec
Minimum step	10nm	10nm
loads	25kg	
orthogonality	< ±2arcsec XY Axis	
environments	Vacuum 5×10^{-5} Pa	
convection	DC: 300nT AC: 20nT	
cleanness	ISO Class 6	
bleeder capacity	$< 3 \times 10^{-6}$ Pa · m ³ /s	



Feature

▶ **Excellent Vacuum Compatibility :**

The platform is engineered and manufactured to rigorous high-vacuum standards, maintaining stable and reliable operation in vacuum environments down to 5×10^{-5} Pa, thereby ensuring a solid foundation for high-precision experiments and production.

▶ **Robust Magnetic Shielding :**

A carefully designed magnetic-shielding structure effectively suppresses external field interference, reducing in-plane magnetic flux density to minimal levels and creating an ideal low-field environment for precision processing and testing.

▶ **Exceptional Dynamic Performance :**

Structural optimizations deliver a lightweight yet rigid platform, combining agility with outstanding stability to achieve smooth, efficient motion under dynamic conditions.



The VMZT series stage is a mechanical motion stage with four degrees of freedom. Designed for the demanding semiconductor industry design associated with back-channel exposure machines and wafer inspection.

Feature

- ▶ X, Y adopts high rigidity, high precision guideway, micron-level running flatness and straightness.
- ▶ ZT axis All-in-one thin and light design, support 360° rotation
- ▶ Z-axis can be kept in place

Specifications

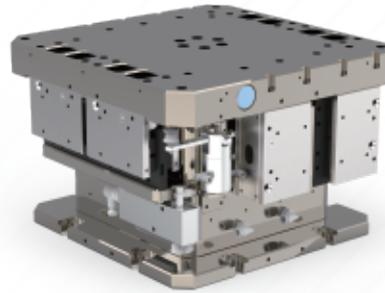
SPECIFICATIONS		
Travel	Scan Axis	400mm,550mm
	Step Axis	400mm,500mm
	Z Axis	4mm
	Rz	±10°
Drive System	Linear Brushless Motor	
Resolution	1nm	
Accuracy	< ±2μm	
Repeatability	< ±0.5μm	
XYZ Position Stability	±0.1μm	
Granite Bass Thickness	250mm	
Rated Payload(Maintaining Dynamic Specifications)	5kg	
Maximum Velocity with Rated Payload	Scan Step Axis	700 mm/s
Peak Acceleration with Rated Payload	Scan Step Axis	0.7G
Stiffness,First Natural Frequency with Rated Payload	>100Hz	
Pitch / Yaw	X Axis	< ±3 arc sec
	Y Axis	< ±4 arc sec
Straightness / Flatness	X Axis	< ±2μm
	Y Axis	< ±2μm
	Z Axis	< ±1.5μm
XY Orthogonality	<2μm	
Velocity ripple(sampled at 100mm/s)	0.25%	
Work Surface - Mounting Surface Parallelism	< 5μm	
MTBF	40,000 hours	

Self-developed motion control components

Mechatronics Systems & Components



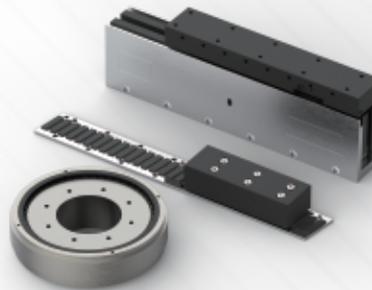
Controller



Active Vibration Isolation System

through rigorous verification tests and practical applications, these core components to ensure the accuracy, stability and reliability of the movement of our products.

As the key components of motion control products, Star Microsystems self-developed product system used in the controller, active vibration isolation system, air bearing axis and motors are all self-developed products.



Motors



Air Bearing Axis

XIVI's multi-point service network responds quickly to customer needs.



National core city outlets

Covering East China, North China, South China, West China, Central China;
Shorten service delivery time by responding nearby.

Professional team linkage

Multi-disciplinary collaboration of electromechanical, software and application engineers;
Rapid diagnosis, remote & on-site support.

7×24 hours technical hotline

Dedicated account manager for one-to-one matchmaking;
Ensure timely communication at critical moments.

Spare parts and training guarantees

Core spares locally stocked and available within 24 hours;
Regular/on-demand on-site training and online courses.

Running

R&D | Production | Services
Wuxi / Shanghai

Services | Sales
Shenzhen / Beijing

Be going to run

R&D | Production | Services
Japan

R&D | Services
Singapore / USA / Taiwan

Services | Sales
Chengdu / Wuhan

 We are expanding into international markets and sincerely invite suppliers to partner with us. If you wish to discuss cooperation, please visit our official website and contact us via our official email sales@xivitech.com





THINKER IN MOTION



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SEEKING BUSINESS PARTNERS

We are expanding into international markets and sincerely invite suppliers to partner with us. If you wish to discuss cooperation, please visit our official website and contact us via our official email sales@xivitech.com